

POWER DISSIPATION (DFN(PLP)1216-6G)

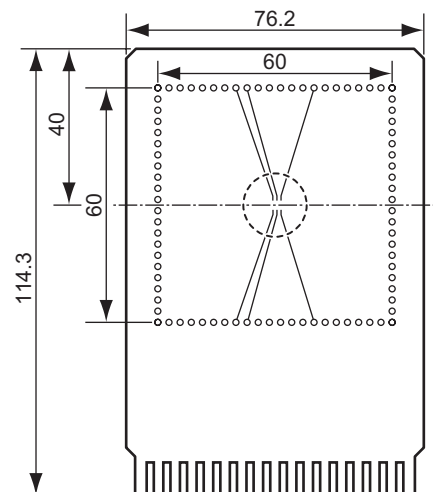
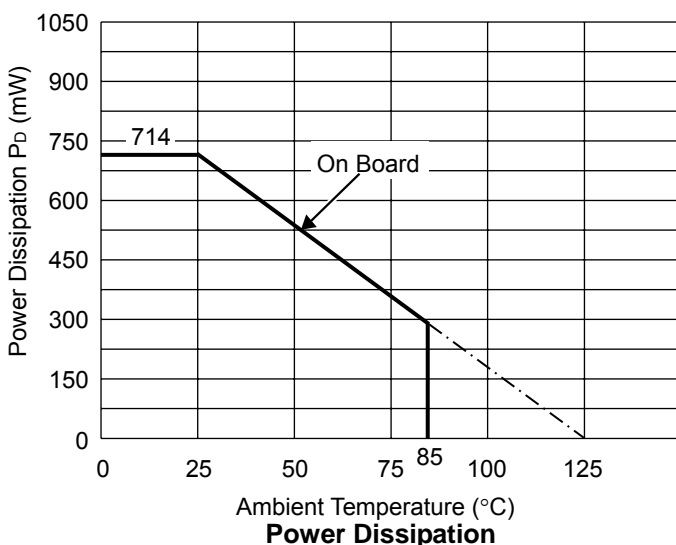
Power Dissipation (P_D) depends on conditions of mounting on board.
 This specification is based on the measurement at the condition below:

Measurement Conditions

	JEDEC STD.51-7 Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (4 Layer)
Board Dimensions	76.2mm×114.3mm×1.6mm
Copper Ratio	Top side, Back side: 60mm×60mm: Approx. 10% 2nd, 3rd Layer: 74.2mm×74.2mm: Approx. 100%
Through-holes	φ 0.85mm x 44pcs

Measurement Results (Ta=25°C, Tjmax=125°C)

	JEDEC STD.51-7 Land Pattern
Power Dissipation	714mW
Thermal Resistance	$\theta_{ja} = (125-25^\circ\text{C})/0.714\text{W} = 140^\circ\text{C/W}$
	$\theta_{jc} = 21^\circ\text{C/W}$



Measurement Board Pattern

○ IC Mount Area (Unit: mm)

RECOMMENDED LAND PATTERN

